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Li et al. (43) **Pub. Date: Nov. 10, 2022**(54) **IMMERSION COOLING SYSTEM AND  
ELECTRONIC APPARATUS HAVING THE  
SAME AND PRESSURE ADJUSTING  
MODULE****Publication Classification**(51) **Int. Cl.**  
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(57) **ABSTRACT**

An immersion cooling system includes a box body, a condensing structure and a pressure adjusting module. The box body has a first containing space, the first containing space is adapted to contain a heat dissipation medium, and at least one heat generating component is disposed in the first containing space to be immersed in the heat dissipation medium which is in liquid state. The condensing structure is disposed in the first containing space and above the heat dissipation medium which is in liquid state. The pressure adjusting module is adapted to actively drive a liquid in the first containing space to flow into the second containing space, such that a pressure in the first containing space is reduced to be less than an external pressure. In addition, an electronic apparatus having the immersion cooling system and a pressure adjusting module are also provided.

